

Subminiature High Performance TS AlGaAs Red LED Lamps

Technical Data

Features

- Subminiature Flat Top Package Ideal for Backlighting and Light Piping Applications
- Subminiature Dome Package Diffused Dome for Wide

Viewing Angle Non-diffused Dome for High Brightness

- Wide Range of Drive Currents 500 µA to 50 mA
- Ideal for Space Limited Applications
- Axial Leads
- Available with lead configurations for Surface Mount and Through Hole PC Board Mounting

Description

Flat Top Package

The HLMP-PXXX Series flat top lamps use an untinted, nondiffused, truncated lens to provide a wide radiation pattern that is necessary for use in backlighting applications. The flat top lamps are also ideal for use as emitters in light pipe applications.

Dome Packages

The HLMP-QXXX Series dome lamps, for use as indicators, use a tinted, diffused lens to provide a wide viewing angle with high on-off contrast ratio. High brightness lamps use an untinted, nondiffused lens to provide a high luminous intensity within a narrow radiation pattern.

Lead Configurations

All of these devices are made by encapsulating LED chips on axial lead frames to form molded epoxy subminiature lamp packages. A variety of package configuration options is available. These include special surface mount lead configurations, gull wing, yoke lead, or Zbend. Right angle lead bends at 2.54 mm (0.100 inch) and 5.08 mm (0.200 inch) center spacing are available for through hole mounting. For more information refer to Standard SMT and Through Hole Lead Bend **Options for Subminiature LED** Lamps data sheet.

HLMP-P106/P156 HLMP-Q10X/Q15X



Technology

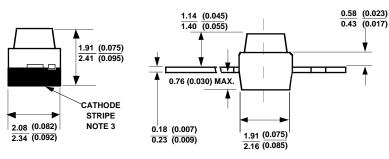
These subminiature solid state lamps utilize a highly optimized LED material technology, transparent substrate aluminum gallium arsenide (TS AlGaAs). This LED technology has a very high luminous efficiency, capable of producing high light output over a wide range of drive currents (500 µA to 50 mA). The color is deep red at a dominant wavelength of 644 nm deep red. TS AlGaAs is a flip-chip LED technology, die attached to the anode lead and wire bonded to the cathode lead. Available viewing angles are 75°, 35°, and 15°.

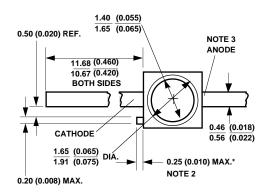
Device Selection Guide

Package Description	$\begin{array}{c} \textbf{Viewing Angle} \\ \textbf{2} \ \theta_{1/2} \end{array}$	Deep Red R _d = 644 nm	$\begin{array}{c} \textbf{Typical Iv} \\ \textbf{I}_{f} = 500 \ \mu \textbf{a} \end{array}$	Typical Iv I _f = 20 mA	Package Outline
Domed, Diffused Tinted, Standard Current	35	HLMP-Q102		160	В
Domed, Diffused Tinted, Low Current	35	HLMP-Q152	2		В
Domed, Nondiffused Untinted, Standard Current	15	HLMP-Q106		530	В
Domed, Nondiffused Untinted, Low Current	15	HLMP-Q156	7		В
Flat Top, Nondiffused, Untinted, Standard Current	75	HLMP-P106		130	А
Flat Top, Nondiffused Untinted, Low Current	75	HLMP-P156	2		А

Package Dimensions

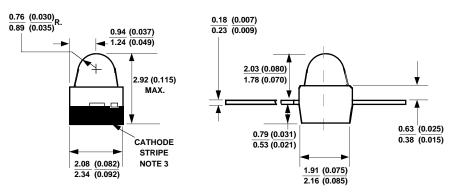






* REFER TO FIGURE 1 FOR DESIGN CONCERNS.

B) Diffused and Nondiffused Dome Lamps



NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETRES (INCHES). 2. PROTRUDING SUPPORT TAB IS CONNECTED TO ANODE LEAD.
- 3. LEAD POLARITY FOR THESE TS AIGaAs SUBMINIATURE LAMPS IS OPPOSITE TO THE LEAD POLARITY OF SUBMINIATURE LAMPS USING OTHER LED TECHNOLOGIES.

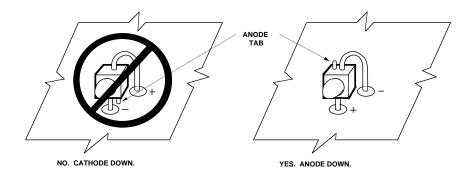


Figure 1. Proper Right Angle Mounting to a PC Board to Prevent Protruding Anode Tab from Shorting to Cathode Connection.

Absolute Maximum Ratings at T_{A} = 25 $^{\circ}C$

Peak Forward Current ^[2]	
Average Forward Current (@ $I_{PEAK} = 300 \text{ mA}$)	^[1,2] 30 mA
DC Forward Current ^[3]	50 mA
Power Dissipation	
Reverse Voltage ($I_R = 100 \ \mu A$)	
Transient Forward Current (10 µs Pulse) ^[4]	500 mA
Operating Temperature Range	55 to +100°C
Storage Temperature Range	55 to +100°C
LED Junction Temperature	110°C
Lead Soldering Temperature	
[1.6 mm (0.063 in.) from body	260°C for 5 seconds
Reflow Soldering Temperatures	
Convective IR 235°C Peak, abov	e 183°C for 90 seconds
Vapor Phase	215°C for 3 minutes

Notes:

1. Maximum $I_{\rm AVG}$ at f = 1 kHz, DF = 10%.

2. Refer to Figure 7 to establish pulsed operating conditions.

3. Derate linearly as shown in Figure 6.

4. The transient peak current is the maximum non-recurring peak current the device can withstand without damaging the LED die and wire bonds. It is not recommended that the device be operated at peak currents above the Absolute Maximum Peak Forward Current.

Part Number HLMP-	LuminousIntensityIV (mcd)@ 20 mA ^[1] Min.Typ.		Total Flux	Peak Wavelength λ _{peak} (nm) Typ.	$\begin{array}{c} \textbf{Color,}\\ \textbf{Dominant}\\ \textbf{Wavelength}\\ \lambda_{d}^{[3]} \ (\textbf{nm})\\ \textbf{Typ.} \end{array}$	Viewing Angle $2\theta^{1/2}$ Degrees ^[4] Typ.	Luminous Efficacy η _v ^[5] (lm/w)
Q106	56	530	280	654	644	15	85
Q102	22	160	-	654	644	35	85
P106	22	130	280	654	644	75	85

Optical Characteristics at $T_A = 25^{\circ}C$

Optical Characteristics at T_{A} = 25 $^{\circ}C$

Part Number (Low Current) HLMP-	$\begin{array}{c c} Luminous\\ Intensity\\ I_V (mcd)\\ @ 0.5 mA^{[1]}\\ Min. \ \ Typ. \end{array}$		Total Flux	Peak Wavelength λ _{peak} (nm) Typ.	$\begin{array}{c} \textbf{Color,}\\ \textbf{Dominant}\\ \textbf{Wavelength}\\ \lambda_{d}^{[3]} \ (\textbf{nm})\\ \textbf{Typ.} \end{array}$	Viewing Angle $2\theta^{1/2}$ Degrees ^[4] Typ.	Luminous Efficacy η _v ^[5] (lm/w)
Q156	2.1	7	10.5	654	644	15	85
Q152	1.3	2	-	654	644	35	85
P156	0.6	2	10.5	654	644	75	85

Notes:

1. The luminous intensity, Iv, is measured at the mechanical axis of the lamp package. The actual peak of the spatial radiation pattern may not be aligned with this axis.

 $2,\,\phi_v\,is$ the total luminous flux output as measured with an integrating sphere.

3. The dominant wavelength, λ_d , is derived from the CIE Chromaticity Diagram and represents the color of the device.

4. $\theta^{1\!/\!2}$ is the off-axis angle where the liminous intensity is 1/2 the peak intensity.

5. Radiant intensity, I_{ν} , in watts/steradian, may be calculated from the equation $I_{\nu} = I_{\nu}/\eta_{\nu}$, where I_{ν} is the luminous intensity in candelas and η_{ν} is the luminous efficacy in lumens/watt.

Part Number HLMP-	Vol V _F (ward ltage Volts) = 20 mA Max.	$\begin{array}{c} Reverse \\ Breakdown \\ V_R \left(Volts \right) \\ @ I_R = 100 \ \mu A \\ Min. \ \ Typ. \end{array}$		Capacitance C (pF) $V_F = 0$, f = 1 MHz Typ.	Thermal Resistance Rθ _{J-PIN} (°C/W)	$\begin{array}{c} \textbf{Speed of Response} \\ \tau_{s} \ (\textbf{ns}) \\ \textbf{Time Constant} \\ e^{\text{-}t/\tau_{s}} \\ \textbf{Typ.} \end{array}$
Q106	1.9	2.4	5	20	20	170	45
Q102	1.9	2.4	5	20	20	170	45
P106	1.9	2.4	5	20	20	170	45

Electrical Characteristics at T_{A} = 25 $^{\circ}C$

Electrical Characteristics at T_{A} = 25 $^{\circ}C$

Part Number (Low Current) HLMP-	Vol V _F (V	ward tage /olts) 0.5 mA Max.	Reverse Breakdown V _R (Volts) @ I _R = 100 μA Min. Typ.		Capacitance C (pF) $V_F = 0$, f = 1 MHz Typ.	Thermal Resistance Rθ _{J-PIN} (°C/W)	$\begin{array}{c} \textbf{Speed of Response} \\ \tau_{s} \ (\textbf{ns}) \\ \textbf{Time Constant} \\ e^{\text{-t}/\tau_{s}} \\ \textbf{Typ.} \end{array}$
Q156	1.6	1.9	5	20	20	170	45
Q152	1.6	1.9	5	20	20	170	45
P156	1.6	1.9	5	20	20	170	45

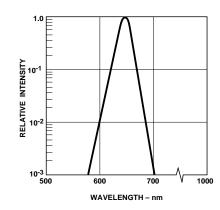


Figure 2. Relative Intensity vs. Wavelength.

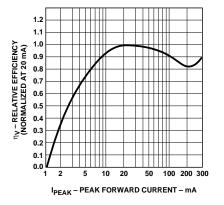


Figure 5. Relative Efficiency vs. Peak Forward Current.

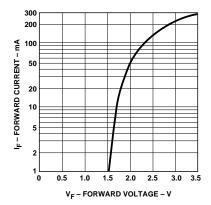


Figure 3. Forward Current vs. Forward Voltage.

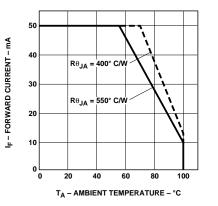


Figure 6. Maximum Forward DC Current vs. Ambient Temperature. Derating Based on $T_JMAX = 110^{\circ}C$.

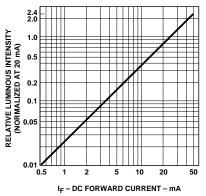


Figure 4. Relative Luminous Intensity vs. DC Forward Current.

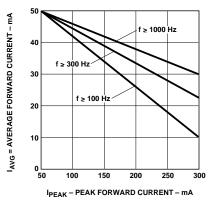


Figure 7. Maximum Average Current vs. Peak Forward Current.

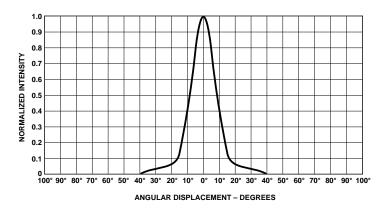


Figure 8. HLMP-Q106/-Q156.

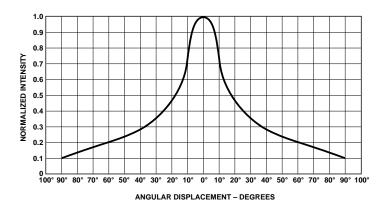


Figure 9. HLMP-Q102/-Q152

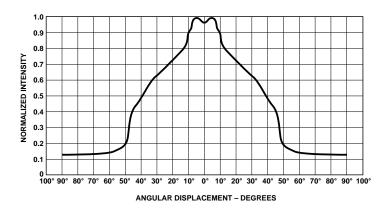


Figure 10. HLMP-P106/-P156.